

Title (en)

Method for producing a semiconductor-molding tablet

Title (de)

Verfahren zur Herstellung eines Harzverkapselungsscheibchens für Halbleiter

Title (fr)

Procédé pour produire une tablette de résine de scellement pour semi-conducteurs

Publication

EP 1498244 B1 20061004 (EN)

Application

EP 04016747 A 20040715

Priority

JP 2003198550 A 20030717

Abstract (en)

[origin: EP1498244A1] A method for producing a semiconductor-molding tablet, which can reduce formation of voids in the package due to increased density of the tablet. The method comprises a step of kneading an epoxy resin composition comprising components (A) an epoxy resin, (B) a phenol resin, and (C) an inorganic filler as essential components, a step of roll-molding the resulting kneaded composition into a sheet shape having a sheet density ratio of 98% or more, a step of pulverizing the resulting sheet-shaped compact, and a step of forming the pulverized material into a tablet shape having a tablet density ratio of 94% or more and less than 98%.

IPC 8 full level

B29B 9/08 (2006.01); **H01L 21/56** (2006.01); **B29B 9/04** (2006.01); **B29B 9/10** (2006.01); **B29B 9/12** (2006.01); **B29C 45/46** (2006.01); **H01L 23/28** (2006.01); **H01L 23/29** (2006.01)

CPC (source: EP KR US)

B29B 9/04 (2013.01 - EP US); **B29B 9/08** (2013.01 - EP US); **B29B 9/10** (2013.01 - EP US); **B29B 9/12** (2013.01 - EP US); **B29C 45/462** (2013.01 - EP US); **H01L 21/56** (2013.01 - KR); **H01L 23/28** (2013.01 - KR); **H01L 23/293** (2013.01 - EP US); **B29K 2063/00** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US)

Designated contracting state (EPC)

DE FR NL

DOCDB simple family (publication)

EP 1498244 A1 20050119; **EP 1498244 B1 20061004**; CN 100339457 C 20070926; CN 1576344 A 20050209; DE 602004002623 D1 20061116; DE 602004002623 T2 20070118; KR 100691063 B1 20070309; KR 20050009234 A 20050124; MY 140808 A 20100115; SG 108956 A1 20050228; TW 200508272 A 20050301; TW I293314 B 20080211; US 2005023715 A1 20050203

DOCDB simple family (application)

EP 04016747 A 20040715; CN 200410071314 A 20040719; DE 602004002623 T 20040715; KR 20040055526 A 20040716; MY PI20042865 A 20040716; SG 200404279 A 20040716; TW 93121334 A 20040716; US 89218604 A 20040716